

REMARKS

The above amendments are proposed relative to the Office Action of September 28, 2000.

Respectfully submitted,

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I hereby certify that this correspondence is being delivered via facsimile to the Commissioner for Patents, Washington, D.C. 20231, Attention Examiner G. Wyszomierski, facsimile number 703-305-7719 on the below date.

Date: _____

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VERSION WITH MARKINGS TO SHOW CHANGES MADE APRIL 23, 2001

In the Claims:

Claims 68-70 have been added.

36. (Amended) A method for reducing voids in a metal material that has been electrolytically deposited into recessed microstructures defined in a surface of a microelectronic workpiece comprising:

[the step of electrolytically depositing a metal to at least partially fill recessed microstructures in the surface of the workpiece; and

then subjecting the surface of the workpiece to an annealing process at a temperature that is at or below about 250 degrees Celsius.

40. (Amended) A method for reducing voids in a metal material that has been electrolytically deposited into recessed microstructures defined on a surface of a microelectronic workpiece comprising:

[the step of electrolytically depositing a metal to at least partially fill recessed microstructures on the surface of the workpiece; and

then subjecting the surface of the workpiece to an annealing process in which the workpiece is subject to a controlled temperature gradient in which the temperature decreases along a cross-section of the workpiece in a direction that is opposite to the direction of the formation of the deposited metal material.

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